

Docket: APS03-003
S/N: 10/742,306

IPW



To:

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

From:

George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No.: 10/742,306	Filed: 12/19/2003
First Named Inventor: Chng Han Shen	
Title: Various Structure/Height Bumps For Wafer Level-Chip Scale Package	
Group Art Unit: 2811	Examiner: Im, Junghwa M.
Attorney Docket: APS03-003	

RESPONSE TO PATENT OFFICE ACTION

Dear Sir:

In response to the office action dated 02/09/06, please consider the following remarks:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on May 9, 2006.

Signature/Date

5/9/06

Stephen B. Ackerman
Reg. No. 37,761